

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
Design Guide 4.1	Unused		
Design Guide 4.2	General Requirements	B	December 2008
Design Guide 4.3	Unused		
Design Guide 4.4	English Bumpered Gullwing Quad Flat Package (PQFP)	A	
Design Registration 4.5	Ball Grid Array and Interstitial Ball Grid Array Package (BGA) and (IBGA)	N.01	November 2018
Design Guide 4.6	Fine Pitch Rectangular Ball Grid Array Package (FRBGA)	D.01	July 2012
Design Guide 4.7	Die-Size Ball Grid Array Package (DSBGA)	E.01	May 2010
Design Guide 4.8	Plastic Quad and Dual Inline Square and Rectangular No Lead Packages (With Optional Thermal Enhancements) (QFN/SON)	C	September 2006
Design Guide 4.9	Generic Matrix Tray for Handling and Shipping (Low Stacking Profile for BGA Packages)	A	April 2000
Design Guide 4.10	Generic Matrix Tray for Handling and Shipping	D	October 2002
Design Guide 4.11	Dual Inline Plastic Family	A	July 1994
Design Guide 4.12	To Be Determined		
Design Guide 4.13	Metric Small Outline J-Leaded Package (SOJ)	A	August 1996
Design Guide 4.14	Ball Grid Array Package (BGA)	J.01	February 2019
Design Guide 4.15	Metric Thin Small Outline Package Type II (TSOPII)	B	May 2004
Design Guide 4.16	Ultra-Thin Plastic No Lead Small Outline Package (UR-PDSO-N)	A	February 1998
Design Guide 4.17	Ball Grid Array (BGA) Package Measurement and Methodology	C	July 2008
Design Guide 4.18	Wafer Level BGA (WLBGA)	A.01	April 2021
Design Guide 4.19	Quad No-Lead Staggered and Inline Multi-Row Packages (With Optional Thermal Enhancements) (QFN)	D	May 2007
Design Guide 4.20	Small Scale Plastic Quad and Dual Inline Square and Rectangular No-Lead Packages (With Optional Thermal Enhancements) (QFN/SON)	F	September 2016
Design Guide 4.21	Internal Stacking Module, Land Grid Array Packages with External Interconnect Terminals (ISM)	A	March 2007
Design Guide 4.22	Fine-Pitch Square Ball Grid Array Package (FBGA) Package on Package (PoP)	D	April 2010
Design Guide 4.23	Punch-Singulated Fine Pitch Square Very Thin and Very-Very Thin Profile Leadframe-Base.d Quad No-Lead Staggered Dual-Row Packages (With Optional Thermal Enhancements) (QFN)	A	November 2005

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

<b>OUTLINE NUMBER</b>	<b>TITLE</b>	<b>ISSUE LETTER</b>	<b>DATE</b>
Design Guide 4.24	Scalable Quad Flat No-Lead Packages, Square and Rectangular (Scalable QFN)	B	August 2016
Design Registration 4.25	Fine-Pitch Land Grid Array Package Square and Rectangular (FLGA, FRLGA)	B	August 2016
Design Registration 4.26	Micropillar Grid Array	B	November 2015
Design Registration 4.27	BGA Package (BGA)	F.01	November 2018

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

<b>OUTLINE NUMBER</b>	<b>TITLE</b>	<b>ISSUE LETTER</b>	<b>DATE</b>
SPP-001	SPP Document Procedures		March 1991
SPP-002	Pin #1 Mark Function and Location		June 1991
SPP-003	Metrication		July 1991
SPP-004	Lead Finish and Base Metal Specification		June 1991
SPP-005	Pin #1 Orientation for TAB Packages		June 1991
SPP-006	Definition of DAMBAR Protrusion and Intrusion		June 1991
SPP-007	Use of "Proposed" on Ballots		June 1991
SPP-008	Gull-wing Lead Dimensioning		September 1991
SPP-009	Inclusion of Nominal Dimensions		September 1991
SPP-010	Grid Array Terminal Position Numbering		September 1991
SPP-011	J Lead Dimensioning of Lead Contact Points		January 1992
SPP-012	Pin #1 Mark and Lead Numbering Convention for Dual-In-Line Packages with Standard and Reverse- Bend Lead Form		January 1993
SPP-013	Registered and Standard Outlines	A	October 2014
SPP-014	Mold Flash Interlead Flash Gate Burrs and Protrusions for Plastic Packages		April 1994
SPP-015	Requirements for Applying Material and Finish Specifications to Selected Mechanical Outlines		May 1995
SPP-016	Inactivation and Rescission		
SPP-017	Standard Overall Profile Height Codes for Packages	C	November 2004
SPP-018	Procedure for Making Editorial Corrections to Published Documents		May 1999
SPP-019	Measuring Stand-Off Heights of Packages	A	June 2001
SPP-020	Rectangular Grid Array Terminal Position Numbering	A	July 2003
SPP-021	JC-11 Change Record Methodology	A	December 2005
SPP-022	Package Thermal Pad Requirements	A	October 2005
SPP-023	Module Insertion Procedure for DIMM and miniDIMM Connectors	B	February 2013
SPP-024	Reflow Flatness Requirements for Ball Grid Array	A	March 2009
SPP-025	Package Variation Designators	C	August 2018

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

<b>OUTLINE NUMBER</b>	<b>TITLE</b>	<b>ISSUE LETTER</b>	<b>DATE</b>
CS-001	Metric Tab Magazine Family	B	March 1996
CS-002	Thin Matrix Tray for Handling/Shipping of PQFP	A	March 1993
CS-003	Thin Matrix Tray for Handling and Shipping of PLCC Packages	B	April 1993
CS-004	FQFP/MQFP Thin Matrix Tray for Handling and Shipping	B	May1996
CS-005	Thin Matrix Tray for Handling/Shipping of TSOP (II)	B	November 1998
CS-006	Metric Tab Tape Carrier Family	A	November 1993
CS-007	LQFP/TQFP Thin Matrix Tray for Handling and Shipping	A	May 1996
CS-008	TSOP I Thin Matrix Tray for Shipping and Handling	A	March 1996

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

<b>OUTLINE NUMBER</b>	<b>TITLE</b>	<b>ISSUE LETTER</b>	<b>DATE</b>
GS-001	Gauge for Header Family		June 1961
GS-002	Gauge for Header Family		September 1962
GS-003 AA-BD	Dual In-Line Gauge	C	March 1993
GS-004	FBDIMM Socket Insertion and Extraction Gauge	A	July 2006
GS-005	DDR3 DIMM Socket Insertion and Extraction Gauge	A	July 2006
GS-006	SMT DDR2 DIMM Socket Coplanarity Measurement Gauge	A	June 2007
GS-007	DDR2 DIMM Socket Insertion and Extraction Force Gauge	A	June 2007
GS-008	DDR3 DIMM Connector Insertion Force Gauge	A	October 2007
GS-009	SMT DDR3 DIMM Socket Coplanarity Measurement Gauge	A	January 2009
GS-010	DDR4 DIMM Socket Insertion and Extraction Force Gauge	C	November 2017

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
MS-001	R-PDIP-T Dual Inline Plastic Family .300" Row Spacing	D	June 1993
MS-002	Leadless Chip Carrier .050" Type A	A	September 1980
MS-003	Leadless Chip Carrier .050" Type B	A	September 1980
MS-004	Leadless Chip Carrier .050" Type C	B	May 1990
MS-005	Leadless Chip Carrier .050" Type D	A	September 1980
MS-006	Leaded Chip Carrier .050" Type A	A	September 1980
MS-007	Leaded Chip Carrier .050" Type A	A	September 1980
MS-008	Leaded Chip Carrier .050" Type B	A	September 1980
MS-009	Leadless Chip Carrier .040"	A	September 1980
MS-010	Dual Inline Plastic Family (R-PDIP-T) .400" Row Spacing	C	November 1993
MS-011	Standard Dual in Line Family .600" Row Spacing (Plastic)	B	June 1988
MS-012	Small Outline (SO) Family Peripheral Terminals 3.75 (.150") Body Width (Plastic)	G.02	September 2020
MS-013	Small Outline (SO) Family Peripheral Terminals 7.50 (.300") Body Width (Plastic)	G	November 2020
MS-014	Single Layer Chip Carrier .040"	A	August 1985
MS-015	Side Brazed Ceramic Dual in Line .300" - .900" Spacing (.100 center)	A	July 1990
MS-016	Plastic chip Carrier Rect. .050"	A	December 1989
MS-017	Ceramic Pin Grid Array Package Family, S-C-GA (.100" Pitch, Cavity Down)	B	June 1993
MS-018	Square Plastic Chip Carrier Family .050" Lead Pitch (S-PQCC-J)	A	June 1993
MS-019	R-PDIP-T Dual in-line (Shrink .070") Plastic Family .300" Row Spacing	B	March 1993
MS-020	R-PDIP-T Dual in-line (Shrink .070") Plastic Family .600" Row Spacing	B	March 1993
MS-021	R-PDIP-T Dual in-line (Shrink .070") Plastic Family .750" Row Spacing	A	March 1993
MS-022	Metric Plastic Quad Flat Pack Family 1.0, 0.8, 0.65 Pitch	B	December 1996
MS-023	Plastic Small Outline J-Lead Package, .300" Wide Body, .050" Pitch (R-PDSO-J/SOJ)	A	March 1995
MS-024	Thin Small Outline Package 10.16mm Body Family	H	June 2006
MS-025 AA-BD	Thin Small Outline Package, 7.62 mm Body Family (R-PDSO-G/TSOP II)	B	December 1999
MS-026	Low/Thin Profile Plastic Quad Flat Package, 2.00 mm Footprint, Optional Heat Slug	D	January 2001

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

<b>OUTLINE NUMBER</b>	<b>TITLE</b>	<b>ISSUE LETTER</b>	<b>DATE</b>
MS-027	PDSO-J	A	June 1995
MS-028	Rectangular Plastic Ball Grid Array 1.27 mm Pitch	C	May 2000
MS-029	Fine Pitch Plastic Quad Flat Package Outline 2.6 mm Footprint	A	August 1997
MS-030	Ceramic Dual-in-Line (DIP) Family, .300" Row Spacing	A	May 1999
MS-031	Ceramic Dual-in-Line (DIP) Family, .400" Row Spacing	A	May 1999
MS-032	Ceramic Dual-in-Line (DIP) Family, .600" Row Spacing	A	May 1999
MS-033	Ceramic Dual Flatpack Family, .050" Pitch	A	July 1999
MS-034	Plastic Square Ball Grid Array Family	G	January 2017

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

<b>OUTLINE NUMBER</b>	<b>TITLE</b>	<b>ISSUE LETTER</b>	<b>DATE</b>
PS-003	DDR4 260 Pin SODIMM Connector	A.01	July 2016
PS-004	UFS Card 6Gb/s UFS Card Socket	A	July 2020
PS-005	DDR5 288 Pin U/R/LR DIMM Connector	B	October 2022
PS-006	DDR5 262 Pin SODIMM Connector	B	October 2022



**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

<b>OUTLINE NUMBER</b>	<b>TITLE</b>	<b>ISSUE LETTER</b>	<b>DATE</b>
TS-001	Plastic Single-in-Line Flange-Mounted	A	August 1989
TS-002	Header Family Insertion Mount (Peripheral Terminals)	A	June 1995
TS-003	Header Family Surface Mounted (Peripheral Terminals)	B	June 1997
TS-004	Flange-Mounted Header Family	A	June 1995
TS-005	Surface-Mounted Header Family	A	June 1995

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

<b>OUTLINE NUMBER</b>	<b>TITLE</b>	<b>ISSUE LETTER</b>	<b>DATE</b>
US-001	Tape Automated Bonding (TAB) Package Family	B	November 1993

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

<b>OUTLINE NUMBER</b>	<b>TITLE</b>	<b>ISSUE LETTER</b>	<b>DATE</b>
CO-001	Magazine Family DIP 7.62 mm Row Spacing	B	May 1978
CO-002	TO-220 Magazine	B	May 1978
CO-003	Magazine Family DIP 7.62 mm Row Spacing	B	May 1978
CO-004	Square Magazine for DIP	B	May 1978
CO-005	Magazine for DIP 7.62, 10.16, 15.24 mm	A	May 1979
CO-006	Magazine for 68-Pin Chip Carrier	A	November 1982
CO-007	Pin Grid Array Pkg., .100" Centers	A	October 1987
CO-008	Fine Pitch Plastic Shipping Tube Family	A	July 1988
CO-009	Tab Tape Carrier 35, 48, 70 mm	A	July 1989
CO-010	Tray for Handling and Shipping of PGA Packages	E	November 1994
CO-011	Tray for Handling and Shipping of CQFP Packages	B	November 1992
CO-012	EIAJ- Tray for Handling and Shipping of Metric QFP Packages	C	November 1992
CO-013	Generic Carrier Family	B	January 1993
CO-014	2" Leaded Quadpack Carrier	A	December 1989
CO-015	Tray for Handling and Shipping of PQFP Packages	B	January 1993
CO-016	Tray for Handling and Shipping of PLCC Packages	B	November 1992
CO-017	Metric TAB Magazine Family	A	August 1991
CO-018	Metric TAB Tape Carrier Family	A	June 1992
CO-019	Magazine Family Metal Coinstack	A	June 1992
CO-020	<b>Replaced by CS-008</b>		March 1996
CO-021	Plastic Magazine Coinstack	A	August 1992
CO-022	Plastic Magazine Plug Family	A	August 1992
CO-023	Plug Family Coinstack Magazine	A	July 1993
CO-024	<b>Replaced by CS-007</b>		November 1994
CO-025	MCR Plug Family, Flat Plastic Tube (Magazine)	A	June 1993
CO-026	MCR Tube Family, Flat Plastic Tube (Magazine)	A	June 1993
CO-027	MQFP High Density Thin Matrix Tray for Shipping and Handling	B	March 1996
CO-028	Thick Matrix Tray for Handling/Shipping of Ball Grid Array Packages	B	October 1995
CO-029	Thin Matrix Tray for Shipping and Handling of Ball Grid Packages	H	September 2002
CO-030	Thin Matrix Mini Tray	A	October 1995
CO-031	Thick Matrix Mini Tray	A	October 1995
CO-032	Thin Matrix Tray for Handling and Shipping Small Outline J Lead Packages	A	April 1996
CO-033	Plastic Chip Carrier Tube Family	A	August 1998
CO-034	Low Profile Matrix Tray for Handling and Shipping Thin Microelectronic Devices	D	February 2003

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

<b>OUTLINE NUMBER</b>	<b>TITLE</b>	<b>ISSUE LETTER</b>	<b>DATE</b>
CO-035	Thin Matrix Tray for Shipping and Handling of Advanced Memory Buffer	A	March 2006
CO-036	Shipping and Handling Tray for DDR5 DIMM Microelectronic Assembly	B	October 2021
CO-038	Shipping and Handling Tray for M.2 Type 2280 SSD Microelectronic Assembly	A	April 2023
CO-039	Shipping and Handling Tray for M.2 Type 2230 Microelectronic Assembly	A	April 2023
CO-040	Shipping and Handling Tray for 1.00 MM CAMM2 Connector	A	August 2023

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
DO-1	Axial Lead, Flanged (see DO-210-AA)	A	Archived – JEP 95
DO-2	Axial Lead, Flanged		Archived – JEP 95
DO-3	Axial Lead, Flanged		Archived – JEP 95
DO-4	Axial Lead, Terminal Stud (see DO-203-AA)	A	
DO-5	Axial Lead, Terminal Stud (see DO-203-AB)	A	Archived – JEP 95
DO-6	Axial Lead, Flanged		Archived – JEP 95
DO-7	Axial Lead, Round Body (see DO-204-AA)	A	Archived – JEP 95
DO-8	Axial Lead, Terminal Stud (see DO-205-AA)	B	June 1971
DO-9	Axial Lead, Terminal Stud (see DO-205-AB)	B	June 1968
DO-10	Stud Mounted with Terminal		Archived – JEP 95
DO-11	Stud Mounted with Terminal		Archived – JEP 95
DO-12	Axial Lead, Flanged		Archived – JEP 95
DO-13	Axial Lead, Round Body (see DO-202-AA)	A	Archived – JEP 95
DO-14	Axial Lead, Round Body (see DO-204-AB)	A	Archived – JEP 95
DO-15	Axial Lead, Round Body (see DO-204-AC)	A	Archived – JEP 95
DO-16	Axial Lead, Round Body (see DO-204-AD)	A	Archived – JEP 95
DO-17	Axial Lead, Flanged		Archived – JEP 95
DO-18	Axial Lead, Round Body		Archived – JEP 95
DO-19	Disc Package		Archived – JEP 95
DO-20	Ceramic Cylinder with Strip Leads		Archived – JEP 95
DO-21	Press Fit		Archived – JEP 95
DO-22	Single-Ended Prong		Archived – JEP 95
DO-23	Double-Ended Prong		Archived – JEP 95
DO-24	Press Fit		Archived – JEP 95
DO-25	Ceramic Cylinder		Archived – JEP 95
DO-26	Axial Lead, Round Body (see DO-204-AE)	A	Archived – JEP 95
DO-27	Axial Lead, Contour-End (see DO-201-AA)	B	Archived – JEP 95
DO-28	Axial Lead, Flanged		Archived – JEP 95
DO-29	Axial Lead, Round Body (see DO-204-AF)	A	Archived – JEP 95
DO-30	Stud Mount with Axial Lead		Archived – JEP 95
DO-31	Circular Tab-Leads		Archived – JEP 95
DO-32	Axial Lead, Plastic		Archived – JEP 95
DO-33	Axial Lead, Single-Ended		Archived – JEP 95
DO-34	Axial Lead, Round Body (see DO-204-AG)	B	Archived – JEP 95
DO-35	Axial Lead, Round Body (see DO-204-AH)	B	Archived – JEP 95
DO-36	Single-Ended Plastic with Shielded Prong	A	Archived – JEP 95
DO-37	Single-Ended Plastic with Shielded Prong	A	Archived – JEP 95
DO-38	Flat-Based Cylinder without Prong	A	Archived – JEP 95
DO-39	Axial Lead, Plastic	A	Archived – JEP 95
DO-40	Cylinder with Perpendicular Lead	A	Archived – JEP 95
DO-41	Axial Lead, Round Body (see DO-204-AL)	A	Archived – JEP 95

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

<b>OUTLINE NUMBER</b>	<b>TITLE</b>	<b>ISSUE LETTER</b>	<b>DATE</b>
DO-42	Cylinder without Prongs	A	Archived – JEP 95
DO-43	Flange-Based Package with Terminal	A	Archived – JEP 95
DO-44	Flange-Based Package with Terminal	A	Archived – JEP 95
DO-45	Axial Lead, Single-Ended	A	Archived – JEP 95
DO-200	Disc Type	E	July 1985
DO-201	Axial Type, Round Body, Tapered-End	B	November 2013
DO-202	Axial Leads, Round	A	Archived – JEP 95
DO-203	Stud-hex Base, Solid Terminals	B	March 1973
DO-204 AA-AH	Lead Mounted Family (Round Lead Axial)	B	January 1976
DO-204 AJ-AM	Lead Mounted Family (Round Lead Axial)	C	July 1997
DO-204 AN-AR	Lead Mounted Family (Round Lead Axial)	B	July 1985
DO-205	Stud-Hex Base, Flex Terminals	C	February 1987
DO-206 AA-AB	Lead Mounted Family (Flat Lead Axial)	A	Archived – JEP 95
DO-207 AA	Leadless Device Family	A	Archived – JEP 95
DO-208	Single-End Press-Fit, Flanged	A	December 1972
DO-209	Single-End Press-Fit, Solid Terminals	A	December 1972
DO-210	Lead Mounted Family (Flange Case)	A	Archived – JEP 95
DO-211	<u>Cancelled</u> - REPLACED by TO-244-AA-AB		
DO-212	Pill Family (Round Lead Axial)	A	Archived – JEP 95
DO-213	Leadless Family	D	September 1988
DO-214	Small Outline Plastic Surface Mount C-Bend	D	April 2003
DO-215	Small Outline Plastic Surface Mount Gull Wing	C	June 1998
DO-216	S-PDSO-G2 Gullwing Plastic Surface-Mount	A	October 1995
DO-217	GADB-N Button Rectifier	A	May 1996
DO-218	Power Outline Plastic Surface Mount C-Bend	C	April 2014
DO-219	Outline Plastic Surface Mount Flat	C	May 2015
DO-220	Small Outline Plastic Surface Mount	B	October 2004
DO-221	Thin Profile Plastic Small Outline Surface Mount	B	August 2018
DO-222	Very Thin Small Outline Plastic Surface Mount	A	May 2006

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

<b>OUTLINE NUMBER</b>	<b>TITLE</b>	<b>ISSUE LETTER</b>	<b>DATE</b>
MO-001 AA-AD	Dual in-line Family 7.62 mm Row Spacing	D	June 1976
MO-001 AE-AH	Dual in-line Family 7.62 mm Row Spacing	D	June 1976
MO-001 AJ-AM	Dual in-line Family 7.62 mm Row Spacing	F	June 1983
MO-001 AN-AP	Dual in-line Family 7.62 mm Row Spacing	B	October 1980
MO-002 AA-AH	Header Family .200" Pin Circle	B	October 1976
MO-002 AJ-AL	Header Family .200" Pin Circle	C	October 1976
MO-003 AA-AD	<b>Replaced by MS-033 Variation AB</b>	A	November 1999
MO-003 AE-AH	<b>Replaced by MS-033 Variation AA</b>	A	November 1999
MO-003 AJ	<b>Replaced by MS-033 Variation AB</b>	A	November 1999
MO-003 AK	<b>Replaced by MS-033 Variation AA</b>	A	November 1999
MO-004 AA	<b>Replaced by MS-033 Variation AB</b>	A	November 1999
MO-004 AB	<b>Replaced by MS-033 Variation AB</b>	A	November 1999
MO-004 AC	<b>Replaced by MS-033 Variation AB</b>	A	November 1999
MO-004 AD	<b>Replaced by MS-033 Variation AA</b>	A	November 1999
MO-004 AE	<b>Replaced by MS-033 Variation AA</b>	A	November 1999
MO-004 AF	<b>Replaced by MS-033 Variation AB</b>	A	November 1999
MO-004 AG	<b>Replaced by MS-033 Variation AC</b>	A	November 1999
MO-004 AH	<b>Replaced by MS-033 Variation AC</b>	A	November 1999
MO-004 AJ	<b>Replaced by MS-033 Variation AB</b>		
MO-004 AK	<b>Replaced by MS-033 Variation AA</b>	A	November 1999
MO-004 AL	<b>Replaced by MS-033 Variation AC</b>	A	November 1999
MO-004 AM	Flatpack Family .300" Width, .050" Pitch	C	November 1999
	<b>RESCINDED</b>		
MO-005	Grid Array Family, .125" Pitch	B	Archived – JEP 95
MO-006 AA-AD	Header Family 5.842 mm Pin Circle	C	October 1976
MO-006 AE-AH	Header Family 5.842 mm Pin Circle	D	October 1976
MO-007	Header Family, .141" Pin Circle	B	Archived – JEP 95
MO-008	Header Family, .100" Pin Circle	B	Archived – JEP 95
MO-009 AA-AB	Header Family, .200 Pin Circle	C	Archived – JEP 95
MO-010	Header Family, .065" Pitch	B	Archived – JEP 95
MO-011	Grid Array Family, 2.54 mm Pitch	B	Archived – JEP 95
MO-012 AA-AB	Quad Header Family, 2.54 mm Pitch	C	Archived – JEP 95
MO-013	Header Family, 11.89 mm Pin Circle	B	Archived – JEP 95
MO-014	Flange-Mounted Family Axial Lead	C	October 1976
MO-015 AA-AD	Dual In Line (DIP) Family 15.24 mm Row Spacing	D	June 1976
MO-015 AE-AH	Dual In Line (DIP) Family 15.24 mm Row Spacing	E	June 1977
MO-015 AJ-AM	Dual In Line (DIP) Family 15.24 mm Row Spacing	E	February 1981
MO-015	R-PDIP-T Dual Inline Plastic Family .600" Row Spacing	G	April 1993
MO-016	Dual In Line Plastic Family .900" Row Spacing	D	May 1990
MO-017	Axial Quad Family 2.54 mm Pitch	B	October 1976

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
MO-018	Flatpack Family 10.16 mm Width, .89 Pitch	C	June 1976
MO-019 AA	<b>Replaced by MS-033 Variation AE</b>	A	November 1999
MO-019 AB	<b>Replaced by MS-033 Variation AF</b>	A	November 1999
MO-019 AC	<b>Replaced by MS-033 Variation AE</b>	A	November 1999
MO-019 AD	<b>Replaced by MS-033 Variation AF</b>	A	November 1999
MO-019 AE	Flatpack Family 10.16 mm Width, 1.27 Pitch	D	November 1999
	<b>RESCINDED</b>		
MO-019 AF	<b>Replaced by MS-033 Variation AF</b>	A	November 1999
MO-020	Flatpack Family 12.70 mm Width, 1.27 Pitch	C	June 1976
MO-021	Flatpack Family 15.24 mm Width, 1.27 Pitch	C	June 1976
MO-022 AA-AD	Flatpack Family 17.780 mm Width, 1.27 Pitch	D	September 1977
MO-022 AE	Flatpack Family 17.780 mm Width, 1.27 Pitch	A	September 1977
MO-023	Flatpack Family 22.86 mm Width, 1.27 Pitch	C	June 1976
MO-024	Dual In Line (DIP) Family 12.70 mm Row Spacing	C	June 1976
MO-025	Flange Mounted Family Axial Lead 12.70 Pin Circle	B	October 1976
MO-026	Standard Dual-in-Line Family .400" Row Spacing (Plastic) .070" Lead Pitch	D	July 1991
MO-027	Leadless Flatpack Family 1.27 mm Terminal Space	A	February 1977
MO-028	Dual In Line (DIP) Family 5.08 mm Row Spacing	B	October 1976
MO-029	Quad In Line (QUIP) Family 5.08/10.16 mm Row Spacing	B	October 1976
MO-030	Quad In Line (QUIP) Family 19.05/23.50 mm Row Spacing	B	October 1976
MO-031	Quad In Line (QUIP) Family 5.08/10.16 mm Row Spacing	D	October 1979
MO-032 AA-AF	Flatpack Family 16.64 mm Width, 1.27 Pitch	C	February 1981
MO-033	Quad In Line (QUIP) Family 17.78/22.86 mm Row Spacing	B	February 1981
MO-034	Quad In Line (QUIP Family) .750/.925" Row Spacing	C	June 1990
MO-035	Single In Line (SIP) Family	A	September 1980
MO-036	Ceramic Dual-In-Line (DIP) Family .300" Row Spacing	B	November 1999
MO-037	<b>Replaced by MS-031</b>		
MO-038	Replaced by MS-032		
MO-039	Ceramic Side Ledged Dual In Line (DIP) Family 22.86 mm Row Spacing	A	April 1981
MO-040	Power Module	C	May 1983
MO-041 AA-AF	.050" Pitch Leadless Rectangular Chip Carrier Family (R-CQCC-N)	C	February 1995
MO-042	.050" Center Leadless Rectangular Chip Carrier Type F	A	February 1983



**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
MO-043	Dual In Line Package 19.05 mm Row Spacing	A	September 1984
MO-044	Leaded Ceramic Chip Carrier .050" Center	A	September 1984
MO-045	Single In Line Power Module	A	September 1984
MO-046	Small Outline (SO) Package Peripheral Terminals 5.30 mm (.200") Wide Body	B	November 1984
MO-047	Plastic Chip Carrier (PCC) Family .050" Leadspring, Square	B	November 1988
MO-048	Plastic Flange-Mounted Header Family Multilead Registration	A	February 1987
MO-049	<b>Not Published</b>		
MO-050	<b>Not Published</b>		
MO-051	<b>Not Published</b>		
MO-052	<b>Replaced by MS-016</b>		
MO-053	<b>Replaced by MO-069</b>		September 1988
MO-054	Zig-Zag (ZIP) In Line Family 2.54mm Row Spacing	A	June 1986
MO-055	Ceramic Single In Line (SIP) Family	A	August 1986
MO-056	Ceramic .025" Center Chip Carrier	A	August 1986
MO-057	Ceramic .020" Center Chip Carrier	A	August 1986
MO-058 AA	<b>Replaced by MS-030 AF</b>		
MO-058 AB	<b>Replaced by MS-030 AG</b>		
MO-059	Small Outline (SO) Package Family 8.4 mm Body Width (Plastic)	B	January 1987
MO-060	.040" 132 Pin Quad Flatpack	B	November 1989
MO-061	<b>Replaced by MS-027</b>		June 1995
MO-062	Ceramic Chip Carrier 0.25" Center	A	April 1987
MO-063	Plastic Small Outline J-Lead (SOJ) .350" Body	A	April 1987
MO-064	30 Circuit Pluggable Single Inline Package (SIP) Tabs on .100" Centers	C	September 1992
MO-065	Plastic Small Outline J-Lead (SOJ) .300 Body Family	A	May 1987
MO-066	S-CPGA-P Pin Grid Array Family, .100" Pitch (Small Outline)	C	April 1994
MO-067	Pin Grid Array Family, .100" Pitch (Large Outline), S-CPGA-P	B	June 1993
MO-068	Edge Clip SIP Module Family .100 Row Centers	B	August 1991
MO-069	Plastic Quad Flat Pack .025" Lead Spacing (Gullwing)	B	October 1990
MO-070	.375" Width Flatpack <b>NOT PUBLISHED</b>	A	August 1987
MO-071	Plastic Thin Lead Package	B	July 1989
MO-072	Zig-Zag Inline Family (ZIP) 0.500" Max Seated Height	B	September 1990
MO-073	Ceramic Top Brazed Dual In Line (DIP) Family .900 (22.86) Row Spacing	A	November 1987

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

<b>OUTLINE NUMBER</b>	<b>TITLE</b>	<b>ISSUE LETTER</b>	<b>DATE</b>
MO-074	Ceramic Bottom Brazed Dual In Line (DIP) Family .900 (22.86) Row Spacing	A	November 1987
MO-075	.50 Center Non-Hermetic Leadless Chip Carrier Quad Series	A	December 1987
MO-076	.050 Center Non-Hermetic Leadless Chip Carrier SO Series	A	December 1987
MO-077	Plastic Small Outline J-Lead Package Family (SOJ), .300" Wide Body, .050" Lead Pitch	D	November 1994
MO-078	Hermetic Flange-Mounted Header Family (Peripheral Terminals) Five Lead 2.54 Spacing	A	February 1988
MO-079	Flanged Family Peripheral lead .125 Pitch	A	March 1988
MO-080 AA-AB	ZIP Module Family 0.050" Pin Centers 0.100" Row Centers	A	September 1988
MO-081	Ceramic Quadpack Family .050" Pitch	A	March 1988
MO-082	Ceramic Quad Flat Pack .025" Lead Spacing (Gullwing)	A	May 1988
MO-083	.100" Center Plastic Pin Grid Array Family	A	December 1988
MO-084	Ceramic Quad Flat Pack 0.50" Lead Spacing (Gullwing)	A	July 1988
MO-085	.040" Center Rectangular Leadless Package (Staggered Terminals)	A	July 1988
MO-086	Low Profile Plastic Quad Flat Pack Family .025 Lead Spacing (Gullwing)	B	June 1990
MO-087	"J" Leaded Ceramic Cerquad Package Family - .050" Pitch	B	August 1991
MO-088 AA-AF	Small Outline J-Lead (SOJ) .300 Body Family (MS-113 body)	A	June 1988
MO-089	Plastic Quad Flat Pack .050" Lead Spacing (Gullwing)	A	November 1988
MO-090 AA-AF	Ceramic Quadpack Family .025" Lead Spacing	B	September 1989
MO-091	Plastic Small Outline J-Lead (SOJ) .350 Body Family	A	February 1989
MO-092	6.35 Mm Width Cerpak Registration	A	April 1989
MO-093	Flange-Mounted Header, 5-Lead	A	February 1990
MO-094	Molded Carrier Ring Family	C	March 1993
MO-095	Dual Incline (Wide Body) Plastic Family .300" Row Spacing	A	September 1989
MO-096	Flange-Mounted Header, 7-Lead	A	February 1990
MO-097	Flange-Mounted Family Axial Lead .500" Pin Circle	A	July 1989
MO-098	Braze Lead Flatpack Registration	A	December 1989
MO-099	Small Outline (SO) Family Peripheral	A	October 1989
MO-100	Multilayer Ceramic Quad Flatpack .20 Spacing	A	November 1989

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

<b>OUTLINE NUMBER</b>	<b>TITLE</b>	<b>ISSUE LETTER</b>	<b>DATE</b>
	Gullwing (256 leads)		
MO-101	48 Pin Flatpack, Top Brazed	A	November 1989
MO-102	Tape Quad Flatpack <b>RESCINDED</b>	A	November 1992
MO-103	<b>Replaced by MS-032</b>	B	August 1999
MO-104	Ceramic Quad Flatpack, 0.25" Pitch, Gullwing Leadform	A	August 1991
MO-105	Thin Small Outline J-Lead (TSOJ) .300" Body, 0.050" Lead Pitch	A	August 1990
MO-106	Flatpack Family .535" Length, .030 Pitch	A	April 1990
MO-107	Ceramic Multilayer Ledged Chip Carrier .050" Pitch, J-Bend	A	May 1990
MO-108	Metric Plastic Quad Flat Pack Family, 1.0, 0.8, 0.65 Pitch PQFP-G/MQFP	C	August 1996
MO-109	Molded Carrier Ring Family	B	March 1993
MO-110	Round Lead, "J" form .050" Center Ceramic Chip Carrier	A	July 1990
MO-111	Round Lead, Gullwing .050" Center Ceramic Chip Carrier	A	July 1990
MO-112	Metric Plastic Quad Flatpack Family 3.9 mm Footprint	B	September 1995
MO-113	Ceramic Quadpack Family 0.25" Lead Spacing With Ceramic Nonconductive Tie Bar	D	August 1997
MO-114	Glass Sealed CQFP Family (GQFP-G)	C	January 1996
MO-115	32 Ld. Flatpack .480" Wide	A	November 1990
MO-116	Pluggable Single In-Line Memory Module (SIMM) With Tabs on .050 Centers	B	June 1998
MO-117	Small Outline Gullead 12 mm Body 0.80 mm Lead Spacing	A	June 1990
MO-118	Shrink Small Outline Package Family, 0.25" Lead Pitch .300" Wide Body Width (R-PDSO-G)	B	June 1993
MO-119	Plastic Small Outline (SO) Package Family With .300" Body Width	B	May 1992
MO-120	Plastic Small Outline (SO) Package Family With .350" Body Width	B	May 1992
MO-121	Plastic Small Outline (SO) Package Family With .330" Body Width	B	May 1992
MO-122	R-PDIP-T Thin Dual In Line Family .300" Row Spacing (Plastic)	A	August 1992
MO-123	Small Outline J-Lead, 12 mm Body 0.80 mm Lead Spacing	A	June 1991
MO-124	Small Outline J-Lead Package Family (SOJ) 12.70 mm Body, 1.27 mm Lead Spacing	B	January 1994

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
MO-125	Ceramic Quad Flatpack .025" Pitch Gullwing Leadform	A	June 1991
MO-126	R-CDCC-N Leadless Small Outline Ceramic Chip Carrier .400" Body, .050" Pitch	B	June 1993
MO-127	Power Dual In-line	A	February 1992
MO-128 AA-BQ	.100" Center Staggered Pin Grid Array Family (Large Outline)	C	January 1997
MO-129	Top Brazed Ceramic Leaded Chip Carrier (.020" Lead Pitch) with Plastic Non-Conductive Tie Bar	A	September 1992
MO-130	Top Brazed Ceramic Leaded Chip Carrier (.015" Lead Pitch) with Plastic Non-Conductive Tie Bar	A	September 1992
MO-131	Top Brazed Ceramic Leaded Chip Carrier (.025" Lead Pitch) with Plastic Non-Conductive Tie Bar	A	September 1992
MO-132	<b>Replaced by MS-025A</b>		
MO-133	<b>Replaced by MS-024</b>		January 1995
MO-134	Ceramic Quad Flatpack Family (CQFP) 0.50 mm Lead Pitch with Ceramic Nonconductive Tie Bar	A	May 1992
MO-135	Thin Small Outline Package 12.70 mm Body Family (R-PDSO-G/TSOP II)	C	November 1993
MO-136	<b>Replaced by MS-026</b>		
MO-137	Plastic Shrink Small Outline Package (SSOP) Family 0.025" pitch 0.150" Body Width	E	March 2010
MO-138	16 Lead Flange Mounted Ceramic Power Package (Type 1), R-CDFM-T16	A	June 1993
MO-139	16 Lead Flange Mounted Ceramic Power Package (Type 2), R-CDFM-T16	A	June 1993
MO-140	18 Lead Flange Mounted Ceramic Power Package, R-CDFM-T16	A	June 1993
MO-141	Vertical Surface Mount Package 0.50 mm Lead Pitch, R-PSIP-X24	A	March 1993
MO-142	Thin Small Outline Package Type I, R-PDSO-G/TSOPII	D	July 2000
MO-143	<b>Replaced by MS-029</b>		June 1997
MO-144	Leadless Small Outline Ceramic Chip Carrier .350" Body, .050" Pitch, R-CDCC-N	A	June 1993
MO-145	S-CPGA-B/SMTPGA .050 Center Ceramic Surface Mount Pin Grid Array Family Registration	A	June 1993
MO-146	Ceramic Flatpack Family .380" Width, .025 Pitch (R-GDFP-F)	A	July 1993
MO-147	Small Outline J-Lead Ceramic Chip Carrier .415" Body, .050" Lead Spacing (R-CDSO-J)	A	July 1993

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

<b>OUTLINE NUMBER</b>	<b>TITLE</b>	<b>ISSUE LETTER</b>	<b>DATE</b>
MO-148	Multichip Module Ceramic Quad Flatpack (S-CQFP)	A	June 1993
MO-149	Tape Ball Grid Array Family	F	October 2003
MO-150	Plastic Shrink Small Outline Package (SSOP) - 5.3mm Body Width, 0.65mm Pitch, 1.25mm Lead Length (R-PDSO-G)	B	January 1994
MO-151	<b>Replaced by MS-034</b>		
MO-152	Plastic Shrink Small Outline Package (SSOP), R-PSDO-G/SSOP	C	January 1996
MO-153	Plastic Thin Shrink Small Outline Package (SSOP) R-PDSO-G/TSSOP/HTSSOP	G	January 2018
MO-154	Shrink Small Outline Package Family, 0.4 mm and .5 mm Lead Pitch, 3.9 mm Wide Body	C	April 1997
MO-155	5-Lead Small Outline Plastic (SOP) Package	A	November 1993
MO-156	Square Ceramic Ball Grid Array Family 1.00, 1.27, and 1.50 mm Pitch	C	April 2005
MO-157	Rectangular Ceramic Ball Grid Array Family 1.00, 1.27, and 1.50 mm Pitch	C	April 2005
MO-158	CBGA-X Ceramic Column Grid Array Family - Square	D	April 2002
MO-159	Ceramic Column Grid Array Family - Rectangular	B	June 1999
MO-160 AA-CC	72-Contact Dual Inline Memory Module (DIMM) Family, 1.27 Lead Centers	B	September 1995
MO-161	100 and 168 Pin Dual Inline Memory Module (DIMM) Family with Multiple Keyways, 1.27 mm Contact Centers	Ff	January 2003
MO-162	Plastic Flat Pack/Heat Slug Package 8 mm Pitch 48 Leads (S-PTFP-G48)	A	November 1993
MO-163	<b>Replaced by MS-028</b>		December 1997
MO-164	Plastic Small Outline Package, 9.90 mm Wide Body Family (R-PDSO-G)	A	January 1994
MO-165	Plastic Small Outline J-Lead, 10.15mm Body Family, .8mm Pitch	C	September 1996
MO-166 AA-AF	Plastic Small Outline Heat Slug Package, 20, 24, 30, 36 Leads	D	November 1999
MO-167	Pluggable Dual Inline Module, 1.27 mm Lead Centers 128-Pins	C	October 1997
MO-168 AA-AB	Plastic Isolated Flange-Mounted Header Family	A	January 1994
MO-169	Plastic Surface Mounted Header Family	B	November 2000
MO-170	68-Pin Card	A	February 1995
MO-171	88-Pin Card	A	February 1995

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
MO-172	Dual Inline Memory Module (DIMM) Family 112 & 300 Pin 1.27 mm Pitch	D	April 1999
MO-173	TFH-PQFP-G/TQHS Thin Quad Heat Spreader Family Registration	A	October 1995
MO-174	Plastic Small Outline Package, 70-pin .8 mm Pitch (R-PDSO-G/SOP)	A	January 1996
MO-175	Plastic Small Outline Package, 12.6 mm Body, 1.27 mm Lead Spacing	A	September 1995
MO-176	Ceramic Zig-Zag Inline Family (2.54 Row Spacing)	A	March 1995
MO-177	200 Pin Small Outline Dual Inline Memory Module (DIMM) Family, 0.65 mm Lead Centers	A	July 2001
	<b>RESCINDED</b>		
MO-178	Plastic Small Outline Package (SOT/SP), 5 Leads	D	September 2020
MO-179	Dual Inline Memory Module (DIMM) Family 1.00 Lead Centers (278-pin)	A	October 1995
MO-180	Plastic Small Outline Package (SOP) 13.3 mm Body Width	B	February 2001
MO-181	Metric Small Outline 16 mm Wide Body J-Lead Package (MSOJ)	A	January 1996
MO-182	Metric Thin Small Outline 16.00 mm Wide Body Package (MTSOP II)	C	September 1996
MO-183	Thin Small Outline Package Type I 0.55 mm Lead Pitch (TSOP I)	A	January 1996
MO-184	Plastic Small Outline Heat Slug Package	B	November 1999
MO-185	72 Pin Staggered Dual Inline Module (SDIM) Family, 1.27 Lead Centers	A	August 1996
MO-186	Solid State Floppy Disk Card (SSFDC)	C	March 1999
MO-187	Plastic Thin Shrink Small Outline Package 0.65 & 0.50 Pitch	F	September 2010
MO-188	Power PQFP Heat Slug Package (H-PQFP - G)	B	February 2000
MO-189	Plastic Quad Flat Heat Slug Package (2.0mm Thick 2.00 mm Footprint Quad & Dual-Sided Leads)	A	March 1996
MO-190	Small Outline Dual Inline Memory Module (DIMM) Family, 0.8 Lead Centers	D	January 2001
MO-191	Dual Inline Memory Module (DIMM) Family 1.27 Lead Centers, 160 Leads	A	December 1996
MO-192	Low Profile Ball Grid Array Family	F	August 2003
MO-193	Plastic Thin Shrink Small Outline Package (Shrink SOT)	G	February 2021
MO-194	Plastic Thin Shrink Small Outline Package 0.40mm Lead Pitch	B	November 1997
MO-195	Thin Fine Pitch Ball Grid Array, 0.50mm Pitch	D	May 2006

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

<b>OUTLINE NUMBER</b>	<b>TITLE</b>	<b>ISSUE LETTER</b>	<b>DATE</b>
MO-196	Plastic Ultra-Thin Small Outline No-Lead Package	C	June 1998
MO-197	Plastic Ultra-Thin Small Outline No-Lead Package	B	November 1997
MO-198	PQFP-B 3-Tier Family	A	April 1997
MO-199	Low Profile Small Outline J-Lead Package (LSOJ)	B	June 1999
MO-200	Small Outline J-Lead Package Assembly 2 High/4 High Stack	B	June 1999
MO-201	2 High/4 High Stacked TSOP II <b>INACTIVATION NOTICE</b>	A	June 2003
MO-202	Vertical Zig Zag Surface Mount Package 0.40mm Lead Pitch	A	March 1998
MO-203	Plastic Thin Shrink Outline Package (Shrink SOT)	C	August 2010
MO-204	Plastic Quad Flat Package Outline With Exposed Heat Sink	B	May 2001
MO-205	Low Profile, Fine Pitch, Ball Grid Array Family, 0.80mm Pitch, (Sq. & Rect.)	F	April 2003
MO-206	Dual Inline Memory Module (DIMM) Family 184 Pin DDR 1.27mm Contact Centers	E	January 2006
MO-207	Square & Rectangular Die-Size Ball Grid Array Family	N	June 2013
MO-208	Plastic Thin Fine Pitch Quad Flat No Lead Package	C	November 2001
MO-209	Plastic Thin Shrink Small Outline No Lead Package	A	November 1998
MO-210	Fine Pitch Ball Grid Array Family Rectangular, 0.80 mm Pitch	Q	January 2021
MO-211	Die Size Ball Grid Array	C	June 2004
MO-212	Rectangular Plastic Quad Flat Package Outline 1.0mm Thick Body 3.20 Footprint	A	November 1998
MO-213	Horizontal Staggered Surface Mount Package 0.40mm Lead Pitch	A	November 1998
MO-214	Micro Dual Inline Memory Module Family, 0.5mm Lead Centers	B	September 2002
MO-215	SDRAM Dual Inline Memory Module (DIMM) Family, 1.00 mm Contact Centers <b>INACTIVATION NOTICE</b>	A	November 2000
MO-216	Plastic Bottom Ball Grid Array Family, 0.80 mm Pitch Square Family	G	January 2021
MO-217	Very Very Thin Quad Bottom Terminal Chip Carrier Family	B	November 2001
MO-218	Plastic Flange-Mounted, Staggered Header Family	A	October 1999
MO-219	Low Profile, Fine Pitch, Ball Grid Array Family, 0.80 mm Pitch. (SQ.& RECT.)	G	January 2007
MO-220	Thermally Enhanced Plastic Very Thin and Very Very Thin Fine Pitch Quad Flat No Lead Package	K.01	August 2011

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
MO-221	Extremely Thin Profile Two Row Cavity Down 0.50 mm Pitch Ball Grid Array Family	C	May 2001
MO-222	Very Thin Profile, Fine Pitch, Land Grid Array Family, 0.50/0.65 mm PITCH, SQ/RECT	B.01	December 2010
MO-223	Plastic Thin Shrink Small Outline Package (Shrink SOT)	A	April 2000
MO-224	200 Pin DDR S.O. DIMM 0.60 mm Lead Centers	E	November 2006
MO-225	Very Thin Profile, Fine Pitch, Ball Grid Array Family 0.50/0.65 mm Pitch, SQ/RECT	C	August 2007
MO-226	Plastic Small Outline Heatslug Package 7.5mm Body Wide, 1.0mm Lead Pitch	B	February 2001
MO-227	DDR SRAM DIMM 1.00 mm Contact Centers	A	May 2003
	<b>INACTIVATION NOTICE</b>		
MO-228	Thin, Fine-Pitch Ball Grid Array Family, Dual Pitch	A	March 2001
MO-229	Thermally Enhanced Plastic Very Thin and Very Thin Fine Pitch Dual Flat No Lead Package	F	August 2012
MO-230	Plastic Small Outline with Exposed Heat Sink	A	March 2001
MO-231	Plastic Surface Mounted Header Family 21.50mm Body Width, 1.40mm LEAD PITCH	A	August 2001
MO-232	Low Profile Plastic Dual Flat No Lead Package	A	August 2001
MO-233	Rectangular Die-Size, Fine Dual Pitch Ball Grid Array Family	C	February 2003
MO-234	Bottom Grid Array, Ball, 1.00 mm Pitch Rectangular Family	E	June 2018
MO-235	Header Family Surface Mounted (Peripheral Terminals)	B	February 2003
MO-236	Plastic Ultra and Super Thin Small Outline, Non-Leaded Package	C	March 2010
MO-237	DDR2 SDRAM DIMM (Dual Inline Memory Module) Family 1.00mm Contact Centers	G.01	April 2011
MO-238	Stacked TSOP II Package Family (2 High)	A	February 2003
MO-239	Thermally Enhanced Plastic Very Thin Dual Row Fine Pitch Quad Flat No Lead Package	A	November 2002
MO-240	Thermally Enhanced 8 Lead 1.27 & 0.65MM Pitch, Low Profile Plastic Dual Flat No Lead Package	C	August 2012
MO-241	Dual Compatible Thermally Enhanced Plastic Very Thin Fine Pith Quad Flat No Lead Package	B	August 2003
MO-242	Rectangular Die-Size, Stacked Ball Grid Array Family .80mm Pitch	C	September 2008
MO-243	Thermally Enhanced Plastic Very Thin and Very Thin Fine Pitch Bumped Quad Flat No lead	A	August 2003
MO-244	244 Pin DDR2 Mini DIMM 0.60 Lead Centers	C	February 2008



**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

<b>OUTLINE NUMBER</b>	<b>TITLE</b>	<b>ISSUE LETTER</b>	<b>DATE</b>
MO-245	High Profile Plastic Thermally Enhanced Enlarged Pitch Dual Flat No Lead Package	A	September 2003
MO-246	Rectangular Fine Pitch Thin Ball Grid Array 0.65 mm Pitch	I	August 2022
MO-247	Plastic Quad No-Lead Staggered Multi-Row Packages	D	May 2007
MO-248	Thermally Enhanced Plastic Ultra Thin and Extremely Thin Fine Pitch Quad Flat No Lead Package	E	June 2006
MO-249	Thin SO Package 8.89mm Body Family	A	January 2004
MO-250	Thermally Enhanced Plastic Very Thin and Very Very Thin Fine Pitch Bumped Quad Flat No Lead Package	A	November 2003
MO-251	Thermally Enhanced Plastic Very Thick Quad Flat No Lead Package	A	February 2004
MO-252	Plastic Very Very Thin Ultra Thin and Extremely Thin Fine Pitch Dual Small Outline Non-Leaded Package	D	March 2010
MO-253	14 & 16 Lead Screw Mount and Surface Mount Power Package	B	February 2008
MO-254	Thermally Enhanced Plastic Low and Thin Profile Fine Pitch Quad Flat No Lead Package	A	February 2004
MO-255	Plastic Very Very Thin Ultra Thin and Extremely Thin Fine Pitch Quad Flat Small Outline Non-Leaded Package	B	October 2005
MO-256	FB DIMM Family 1.00mm Contact Centers	F	June 2007
MO-257	Plastic Fine Pitch Quad No-Lead Staggered Two Row Thermally Enhanced Package Family	B	May 2005
MO-258	200 PIN DDR Mini DIMM 0.60 Lead Centers	A	December 2004
MO-259	Very Very Thin Small Outline Package Family	A	March 2005
MO-260	DDR and DDR2 Micro DIMM Mezzanine 214 Pin 0.4mm Lead Centers	C	January 2007
MO-261	Thick & Very Thick Fine Pitch Rectangular Ball Grid Array Family 0.80mm Pitch	A	June 2005
MO-262	Thermal Enhanced (Top Side) Plastic Very Thin and Very Very Thin Fine Pitch Quad Flat No Lead Package	A	September 2005
MO-263	Plastic Very Thin and Very Very Thin Fine Pitch Quad Flat No Lead Package	A	September 2005
MO-265	Thermally Enhanced Plastic Very Thin Fine Pitch Quad Flat No Lead Package Including Corner Terminals	A	November 2005

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
MO-266	Very Thin, Fine-Pitch, Stackable Ball Grid 0.50 mm Ball Pitch Array Family	C	January 2009
MO-267	Thermally Enhanced Plastic Very Thin Fine Pitch Quad Flat No Lead Package	B	March 2006
MO-268	204 Pin DDR3 S.O. DIMM 0.60 Lead Centers	E	March 2014
MO-269	DDR3 SDRAM DIMM 1.00mm Contact Centers	I	February 2014
MO-270	Extra Thin Profile, Fine Pitch, Internal Stacking Module (ISM) With Single Interconnect Array 0.75/0.80 mm Pitch SQ/RECT	B	June 2008
MO-271	Exposed Pad Plastic Small Outline Family 7.60 mm Body Width	A	May 2006
MO-272	Low Profile Exposed Pad Plastic Small Outline Family 3.90mm Body Width	A	May 2006
MO-273	Upper POP Package, Square, Fine Pitch, Ball Grid Array (0.65 and 0.50 mm Pitch)	C	March 2011
MO-274	DDR1/DDR2 16b/32b Small Outline Dual Inline Memory Module (SO-DIMM) Family 0.8 Lead Centers	D	October 2014
MO-275	Low Profile, Fine Pitch Ball Grid Array Family (SQ)	A.01	July 2011
MO-276	Fine Pitch Ball Grid Array Family, Rectangular, 0.50mm Pitch FR-XBGA	U	August 2023
MO-277	13 Pin Full Size MultimediaCard (MMC) Outline- MMCplus 32 X 24 X 1.4mm	A	September 2006
MO-278	13 Pin Reduced Size MultimediaCard (MMC) Outline-MMCmobile 18 X 24 X 1.4mm	A	September 2006
MO-279	10 Pin Micro Size MultimediaCard (MMC) Outline- MMCmicro 14 X 12 X 1.1mm	A	September 2006
MO-280	Ultra Thin and Very, Very Thin Profile, Fine Pitch Ball Grid Array Family (SQ.)	A	September 2006
MO-281	DDR2 SDRAM DIMM (Dual Inline Memory Module ) Family, Flex-Based, 1.00mm Contact Centers	A	November 2006
MO-282	FB DIMM Family, Flex Based, 1.00 mm Contact Centers	A	January 2007
MO-283	Plastic Super-Thin And Die-Thin Profiles RFID Dipole Straps	B	January 2008
MO-284	Thin, Fine-Pitch, Rectangular Dual Pitch Ball Grid Array Family 0.80mm x 1.00mm Pitch	A	May 2007
MO-285	Very Thin Fine-Pitch Ball Grid Array Family Rectangular 0.50/0.65/0.80 mm Pitch	A	August 2007

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

<b>OUTLINE NUMBER</b>	<b>TITLE</b>	<b>ISSUE LETTER</b>	<b>DATE</b>
MO-286	Plastic Small Outline, Wide Body SOIC, 7.5 Body Width, 0.65 Pitch	B	January 2015
MO-287	Small Scale, Plastic, Ultra, Extra and Super Thin, Fine Pitch, Dual Small Outline, No Lead Package	A	September 2007
MO-288	Small Scale Plastic Ultra Extra and Super Thin Fine Pitch Quad Flat No Lead Package (With Optional Thermal Enhancements)	B	September 2009
MO-290	DDR3 SDRAM DIMM Family Flex-Based, 1.00mm Contact Centers	A	November 2007
MO-291	Very Thin Fine Pitch Plastic Quad Flat Package 2.00mm Footprint	B	December 2008
MO-292	Very Thin Fine Pitch Plastic Quad Flat Package, 2.00mm Footprint	C	April 2010
MO-293	Plastic, Ultra, Extra and Super Thin Fine Pitch Dual Small Outline, Flat, Leaded Package	B	September 2021
MO-294	Very Thin Profile, Fine Pitch, SQ Bump Grid Array Family	A	December 2008
MO-295	Thin Profile Interstitial Fine Pitch Ball Grid Array Family (SQ)	A	January 2009
MO-296	Scalable Quad Flat No-Lead Packages, Square and Rectangular	B	January 2012
MO-297	SLIM LITE SSD Assembly	A	May 2009
MO-298	Thin, Very-Thin, Very Very Thin Profile Fine Pitch Ball Grid Array Family 0.40 mm Pitch	A	June 2009
MO-299	Surface Mount Power Package, Fused Leads	B	January 2015
MO-300	mSATA SSD Assembly	C	March 2015
MO-301	Standard & Low, Fine Pitch Rectangular BGA Family 0.65mm Pitch	A	May 2010
MO-302	Very Thin Fine-Pitch Fully Overmolded Stackable Ball Grid Array Family 0.4mm Ball Pitch	C	August 2016
MO-303	Land Grid Array, Rectangular, 0.5 mm Pitch	B	March 2012
MO-304	100/170 Ball Grid Array Family Rectangular 1.0mm Pitch	D	July 2013
MO-305	Wide I/O Micropillar Grid Array Package (MPGA)	C	October 2013
MO-306	Flange Mounted Family Surface Mount (Peripheral Terminals)	A	February 2011
MO-307	Dual-Pitch Rectangular BGA Package 0.50mm X 0.65mm Pitch	A	December 2011
MO-308	Thick Thermally Enhanced Fine Pitch Square BGA Family	A	April 2012
MO-309	288 Pin DDR4 DIMM 0.85mm Pitch	F	March 2015

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
MO-310	256 Pin DDR4 SODIMM and GDDR5M Outline 0.50 mm Pitch	C	February 2014
MO-311	Dual-Pitch Very Thin Profile Rectangular Fine Pitch BGA Package 0.80 mm X 0.65 mm Pitch	F	October 2022
MO-312	4 Lead Flat and Gullwing Surface Mount Power Package	A	February 2013
MO-313	Fine Pitch BGA Family Square 0.50mm Pitch	A	August 2014
MO-314	288 Pin DDR4 Mini DIMM, 0.50mm Pitch	A.01	May 2015
MO-315	Dual Pitch Number BGA Family, Square, 0.80 mm Major, 0.65 mm Minor Pitch	A	February 2015
MO-316	HBM Micropillar Grid Array Package (MPGA)	B	April 2019
MO-317	Upper POP BGA Square 0.40MM Pitch	C	January 2018
MO-318	BGA, Square, 1.00 MM Pitch	B	January 2017
MO-319	6 Lead Surface Mount Power Package with Fused Leads	A	February 2016
MO-320	12 Pin UFS Card 0.91 MM Pitch	B	September 2020
MO-321	Upper PoP BGA Family Square 0.50 MM Pitch (S-XBGA)	A.01	March 2017
MO-322	Upper PoP BGA Family Square 0.65 MM Pitch (S-XBGA)	A.01	March 2017
MO-323	Upper PoP BGA Family Square 0.40 MM Pitch (R-XBGA)	A.01	March 2017
MO-324	Lower PoP BGA Family Square 0.50 MM Top 0.50 MM Bottom Pitch (S-XBGA)	A	August 2016
MO-325	Lower PoP BGA Family Square 0.65 MM Top 0.50 MM Bottom Pitch (S-XBGA)	A	August 2016
MO-326	Lower PoP BGA Family Square 0.80 MM Top 0.50 MM Bottom Pitch (S-XBGA)	A	August 2016
MO-327	9 Lead Surface Mount Power Package, 1.2 mm Pitch H-PSOF	A	September 2016
MO-328	Ball Grid Array Family, Rectangle, 0.755 mm Pitch	B	February 2020
MO-329	288 Pin DDR5 DIMM, 0.85 MM Pitch	F	August 2023
MO-330	Ball Grid Array Family Rectangular, 0.60 mm x 0.70 mm Pitch PDSO-F2	A	June 2018
MO-331	Bottom Grid Array Ball, Square, 1.00 mm Pitch	A	June 2018
MO-332	Plastic Multi Small Outline, 17 Terminal, 1.20 mm Pitch Package. PMSO-E17	A	August 2018
MO-333	Plastic Bottom Flatpack 35 Terminal Package. PQFP-N35	A	August 2018
MO-334	Plastic Single Sided Hardware 7 Wire 1.2 mm Pitch Package. P-PSXH-W7_I120	A	September 2018

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

<b>OUTLINE NUMBER</b>	<b>TITLE</b>	<b>ISSUE LETTER</b>	<b>DATE</b>
MO-336	Plastic Bottom Grid Array, Ball 0.70 mm Pitch, Square Family	A	November 2018
MO-337	262 Pin SODIMM, 0.50 mm Pitch Package	B	February 2022
MO-338	Plastic Bottom Grid Array Ball, 0.80 MM x 0.70 MM Pitch Rectangular Family Package	A	September 2019
MO-339	Plastic Bottom Flatpack 28 Terminal Package	A	September 2019
MO-340	Plastic Dual Small Outline Surface Terminal, Wettable Flank Package	C	March 2022
MO-341	Plastic Quad Flatpack, 8 Terminal, 1.27 mm Pitch Package	B	August 2023
MO-342	Plastic Bottom Grid Array Ball, 0.65 mm Pitch Square Family Package	A	January 2020
MO-343	Plastic Dual Small Outline Surface, 2 Terminal, Wettable Flank Package	B	March 2022
MO-344	Upper Pop Plastic Bottom BGA 0.40MM Pitch Rectangular Family Package	B	August 2023
MO-345	Plastic Dual Small Outline Gull Wing Package, 1.10 mm Thick	A	October 2020
MO-346	Plastic Quad Flatpack, 0.65 mm Pitch, 3.30 mm Body, Square Family Package	A.01	June 2023
MO-347	39 Pin Removable Memory, 1.00 mm Pitch Microelectronic Assembly	A	March 2021
MO-348	Metal Enclosure for SSD Devices, E1.S and M.2	A	July 2021
MO-349	Silicon Bottom Grid Array Column, 0.048 mm x 0.055 mm Pitch Square Package	A.01	August 2022
MO-350	Plastic Bottom Grid Array Ball, 0.35 mm x 0.40 mm Pitch Rectangular Family Package	A	November 2021
MO-351	Plastic Dual Small Outline, 1.00 MM Pitch 5.48 MM width Rectangular Family	A	June 2022
MO-352	Plastic Bottom Grid Array Ball, 0.40 MM Pitch Rectangular Family	A.01	March 2023
MO-353	Plastic Bottom Grid Array Ball, 0.75 MM x 0.73 MM Pitch Rectangular Family	A	August 2022
MO-354	Plastic Multi Small Outline, 1.14 MM pitch, 15.40 MM Body Width, Rectangular Family	A	August 2022
MO-355	Plastic Quad Flat Package, Gull Wing and J-Lead, 0.65 MM Pitch	A	April 2023
MO-356	Plastic Quad Flatpack 1.27 mm Pitch, 5.00 mm X 6.00 mm Rectangular Family Package		August 2023
MO-357	LPDDR5 CAMM2, 1.38 mm X 1.00 mm PITCH Microelectronic Assembly		August 2023

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
SO-001	240 Pin DDRII SDRAM, 1.00mm Contact Centers	B	July 2003
SO-002	244 Pin MINIDIMM 0.60mm Lead Centers	B	February 2008
SO-003	FB DIMM 240 Position Socket Outline 1.00mm Contact Centers	B	August 2006
SO-004	Connector Outline for DDR and DDR2 Micro DIMM Mezzanine 214 Pin 0.4mm Lead Centers	A	May 2005
SO-005	200 Pin Mini DIMM 0.60 mm Lead Centers	A	September 2005
SO-006	204 Pin SO-DDR3 SDRAM, 0.60mm Contact Centers, Socket Outline	B	October 2007
SO-007	DDR3 DIMM 240 Position Socket Outline 1.00mm Contact Centers	B	September 2008
SO-008	144 Pin, DDR1/DDR2 16b/32b Small Outline Dual Inline Memory Module (SO-DIMM) Family, 0.8 Lead Centers, Dual Notch, Socket Outline	B	October 2012
SO-009	DDR2 DIMM 240 Pin SMT Socket Outline 1.00mm Contact Centers	A	March 2007
SO-011	240 Pin DDR2 DIMM 1.00 mm Contact Centers Press Fit Socket Outline	A	September 2007
SO-012	240 Pin DDR3 DIMM 1.00 mm Contact Centers Press Fit Socket Outline	A	September 2007
SO-013	240 Pin FBDIMM 1.00 mm Contact Centers Press Fit Socket Outline	A	September 2007
SO-014	DDR3 DIMM 240 Pin SMT Socket Outline 1.0 mm Contact Centers	A	July 2008
SO-015	mSATA SSD 0.80 mm Pitch	A	December 2011
SO-016	DDR4 DIMM PTH 284 Pin Socket Outline 0.8 MM Pitch	C	August 2014
SO-017	DDR4 DIMM SMT 284 Pin Socket Outline 0.85 MM Pitch	C	August 2014
SO-018	DDR4 and GDDR5M SODIMM 256 Pin Socket 0.50MM Pitch	C	July 2015
SO-019	DDR4 DIMM Press Fit 284 Pin SO 0.85 Pitch	C	August 2014
SO-021	DDR4 Mini DIMM SMT 288 Pin Socket Outline 0.50 mm Pitch	A	February 2015
SO-022	12 Pin UFS Socket Outline 0.91 MM Pith (SKT)	A	August 2016
SO-023	DDR5 DIMM SMT Pin Socket Outline 0.85 MM Pitch	C	September 2020
SO-024	262 Pin DDR5 SODIMM, 0.50 mm Pitch Socket	A	April 2019
SO-025	Plastic Dual Connector	B	March 2022
SO-026	Battery Cell R/A T/H Type Connector, 1.2 mm Pitch	A	October 2021
SO-027	Battery Cell Wire Side Connector, 1.2 mm Pitch	A	October 2021

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

<b>OUTLINE NUMBER</b>	<b>TITLE</b>	<b>ISSUE LETTER</b>	<b>DATE</b>
SO-028	Battery Cell R/A SMT Type Connector, 1.2 mm Pitch	A	October 2021
SO-029	Enclosure Form Factor for Automotive SSD Connector, Cable Mount	A	January 2022
SO-030	Enclosure Form Factor for Automotive SSD Connector, Board Mount	A	February 2022
SO-031	Plastic Multi Connector 32 Pin, 1.00 MM Pitch 19.35 MM x 21.00 MM Socket	A	August 2022
SO-32	Plastic Dual Upper to Bottom, 1.8 mm x 1.00 mm Pitch Connector (CMT)	A	July 2023

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

<b>OUTLINE NUMBER</b>	<b>TITLE</b>	<b>ISSUE LETTER</b>	<b>DATE</b>
TO-1	Metal Can		Archived – JEP 95
TO-2	Metal Can		Archived – JEP 95
TO-3	Diamond Base, .430 Pin Spacing	A	Archived – JEP 95
TO-4	<b>MISSING</b>		
TO-5	Axial Leads, .200 Pin Circle	A	Archived - JEP 95
TO-6	Press Fit		Archived – JEP 95
TO-7	Metal Can		Archived – JEP 95
TO-8	Axial Leads, .281 Pin Circle	A	Archived – JEP 95
TO-9	Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-10	Stud-Mount, Solid Terminals		Archived – JEP 95
TO-11	Metal Can with Flange		Archived – JEP 95
TO-12	Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-13	Metal Can with Rigid Terminals		Archived – JEP 95
TO-14	Stud-Mount, Rigid Terminals		Archived – JEP 95
TO-15	Stud-Mount, Rigid Terminals		Archived – JEP 95
TO-16	Metal Can with Flange		Archived – JEP 95
TO-17	4 Axial Leads .071 Pin Circle		Archived – JEP 95
TO-18	Axial Leads, .100 Pin Circle	A	Archived – JEP 95
TO-19	<b>MISSING</b>		
TO-20	<b>MISSING</b>		
TO-21	<b>MISSING</b>		
TO-22	Flat Metal Can with Flange		Archived – JEP 95
TO-23	Cylindrical Metal Can with Flange		Archived – JEP 95
TO-24	Cylindrical Metal Can with Flange		Archived – JEP 95
TO-25	Cylindrical Metal Can with Flange		Archived – JEP 95
TO-26	Stud-Mounted Metal Can with Flange		Archived – JEP 95
TO-27	Diamond Flange with Holes and Rigid Leads		Archived – JEP 95
TO-28	Metal Can with Flange		Archived – JEP 95
TO-29	Metal Can with Flange		Archived – JEP 95
TO-30	Metal Can with Flange		Archived – JEP 95
TO-31	Metal Can with Stud Mount		Archived – JEP 95
TO-32	Metal Can with Stud Mount		Archived – JEP 95
TO-33	4 Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-34	<b>MISSING</b>		
TO-35	<b>MISSING</b>		
TO-36	Stud-Mount .345 Pin Circle		Archived – JEP 95
TO-37	Diamond Base, .200 Pin Circle	A	Archived – JEP 95
TO-38	Cylindrical Metal Can with Flexible Leads		Archived – JEP 95
TO-39	Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-40	Cylindrical Metal Can with Flange and Flexible Leads		Archived – JEP 95



**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
TO-41	Diamond Base, .430 Pin Circle	A	Archived – JEP 95
TO-42	Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-43	Cylindrical Metal Can with Flange and Flexible Leads		Archived – JEP 95
TO-44	Cylindrical Metal Can with Flange and Flexible Leads		Archived – JEP 95
TO-45	Cylindrical Metal Can with Flange and Flexible Leads		Archived – JEP 95
TO-46	Axial Leads, .100 Pin Circle	A	Archived – JEP 95
TO-47	Cylindrical Metal Can with Flange and Flexible Leads		Archived – JEP 95
TO-48	Stud-Mount, Solid Leads	B	Archived – JEP 95
TO-49	Stud-Mount, Braided Terminal	B	Archived – JEP 95
TO-50	Strip Line Package		Archived – JEP 95
TO-51	Strip Line Package		Archived – JEP 95
TO-52	Axial Leads, .100 Pin Circle		Archived – JEP 95
TO-53	Flange-Mount, Rigid Leads		Archived – JEP 95
TO-54	Metal Can with Flange		Archived – JEP 95
TO-55	Metal Can with Flange		Archived – JEP 95
TO-56	Metal Can with Flange		Archived – JEP 95
TO-57	Stud-Mount, Flexible Leads		Archived – JEP 95
TO-58	Metal Can with Flange Mount		Archived – JEP 95
TO-59	Stud-Mount, Solid Terminals		Archived – JEP 95
TO-60	Stud-Mount, Solid Terminals		Archived – JEP 95
TO-61	Stud-Mount, Solid Terminals		Archived – JEP 95
TO-62	Stud-Mount, Solid Terminals		Archived – JEP 95
TO-63	Stud-Mount, Solid Terminals		Archived – JEP 95
TO-64	Stud-Mount, Solid Terminals		Archived – JEP 95
TO-65	Stud-Mount, Solid Terminals		Archived – JEP 95
TO-66	Diamond Base, .200 Pin Spacing	A	Archived – JEP 95
TO-67	Stud-Mount Metal Can with Rigid Leads		Archived – JEP 95
TO-68	Stud-Mount Metal Can with Rigid Leads		Archived – JEP 95
TO-69	Metal Can with Flange, 12 Leads		Archived – JEP 95
TO-70	Metal Can with Flange, 8 Leads		Archived – JEP 95
TO-71	8 Axial Leads .141 Pin Circle		Archived – JEP 95
TO-72	4 Axial Leads, .100 Pin Circle	A	Archived – JEP 95
TO-73	12 Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-74	10 Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-75	6 Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-76	8 Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-77	8 Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-78	8 Axial Leads, .200 Pin Circle	A	Archived – JEP 95

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

<b>OUTLINE NUMBER</b>	<b>TITLE</b>	<b>ISSUE LETTER</b>	<b>DATE</b>
TO-79	8 Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-80	8 Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-81	Stud-Mount Metal Can with Flange		Archived – JEP 95
TO-82	Stud-Mount Metal Can with Flange		Archived – JEP 95
TO-83	Stud-Mount, Double End	B	Archived – JEP 95
TO-84	Multiple-Ended 14-Lead Flatpack	B	Archived – JEP 95
TO-85	Multiple-Ended 14-Lead Flatpack	A	Archived – JEP 95
TO-86	Multiple-Ended 14-Lead Flatpack	A	Archived – JEP 95
TO-87	Double-Ended 14-Lead Flatpack	A	Archived – JEP 95
TO-88	Double-Ended 14-Lead Flatpack	A	Archived – JEP 95
TO-89	Double-Ended 10-Lead Flatpack	B	Archived – JEP 95
TO-90	Double-Ended 10-Lead Flatpack	A	Archived – JEP 95
TO-91	Double-Ended 10-Lead Flatpack	A	Archived – JEP 95
TO-92	Axial Leaded, Flat Index	A	Archived – JEP 95
TO-93	Stud-Mount, Flex Leads	B	Archived – JEP 95
TO-94	Stud-Mount, Flex Leads	B	Archived – JEP 95
TO-95	Double-Ended 14-Lead Flatpack	A	Archived – JEP 95
TO-96	10 Axial Leads, .230 Pin Circle	A	Archived – JEP 95
TO-97	10 Axial Leads, .230 Pin Circle	A	Archived – JEP 95
TO-98	In-Line Axial Leads, Indexed	C	Archived – JEP 95
TO-99	8 Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-100	10 Axial Leads, .230 Pin Circle	A	Archived – JEP 95
TO-101	12 Axial Leads, .230 Pin Circle	A	Archived – JEP 95
TO-102	Stud-Mount, Flex Leads		Archived – JEP 95
TO-103	Stud-Mount with Rigid Leads	A	Archived – JEP 95
TO-104	Metal Can with Tab, 4 Leads	A	Archived – JEP 95
TO-105	Epoxy Cylinder with Axial Leads	A	Archived – JEP 95
TO-106	Epoxy Cylinder with Axial Leads	A	Archived – JEP 95
TO-107	Metal Can with Flange, Cylindrical	A	Archived – JEP 95
TO-108	Stud-Mount with Flexible Terminals	A	Archived – JEP 95
TO-109	Flange-Mount with Terminals	A	Archived – JEP 95
TO-110	Epoxy with Axial Leads, 10 Leads	A	Archived – JEP 95
TO-111	Stud-Mount, Solid Leads	A	Archived – JEP 95
TO-112	Metal Can with Flange	A	Archived – JEP 95
TO-113	Strip Line with Metal Can	A	Archived – JEP 95
TO-114	Stud-Mount, 4 Solid Terminals	A	Archived – JEP 95
TO-115	Stud-Mount with Rigid Leads	A	Archived – JEP 95
TO-116	DIP, .300 Wide	A	Archived – JEP 95
TO-117	Lateral, 4 Flat Leads	A	Archived – JEP 95
TO-118	Stud-Mount, Flex Leads	A	Archived – JEP 95
TO-119	Strip Line Package , 3 Leads	A	Archived – JEP 95
TO-120	Strip Line Package, 4 Leads	A	Archived – JEP 95

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
TO-121	Cylindrical Metal Can with Perpendicular Leads	A	Archived – JEP 95
TO-122	Leadless Inverted Device	A	Archived – JEP 95
TO-123	Diamond Base, .200 Pin Circle	A	Archived – JEP 95
TO-124	Diamond Base, .200 Pin Circle	A	Archived – JEP 95
TO-125	Metal Can with Flange	A	Archived – JEP 95
TO-126	Flat Lead, .090 Pin Spacing	A	Archived – JEP 95
TO-127	Flat Lead, .166 Pin Spacing	A	Archived – JEP 95
TO-128	Stud-Mount, Lateral 4 Flat Leads	A	Archived – JEP 95
TO-129	Stud-Mount, Lateral 4 Flat Leads	A	Archived – JEP 95
TO-130	Strip Line Package, 4 Leads	A	Archived – JEP 95
TO-131	Strip Line Package, 4 Leads	A	Archived – JEP 95
TO-132	Stud-Mount with Flexible Leads	A	Archived – JEP 95
TO-200 AA-AD	Disc Type Family	I	April 1984
TO-200 AE-AF	Disc Type Family	J	July 1985
TO-201	Coaxial Family	B	Archived – JEP 95
TO-202	Tab-Mounted Peripheral Leads	F	February 1978
TO-203	Press-Fit Family - Solid Leads	C	Archived – JEP 95
TO-204 AA-AE	Flange-Mounted Header Family (.430) Pin Spacing	C	November 1982
TO-205	Header Type .200 Pin Circle	E	November 1982
TO-206	Header Type .100 Pin Circle	B	November 1982
TO-207	Stud-Header Family, .690 Pin Circle	A	Archived – JEP 95
TO-208 AA-AD	Stud Hex Base Family (Solid Terminals)	A	June 1974
TO-208 AE-AG	Stud Hex Base Family (Solid Terminals)	C	May 1979
TO-209	Stud-Hex, Flexible Terminals	A	June 1974
TO-210 AA-AE	Stud-Hex Base Family (Solid Terminals)	A	Archived – JEP 95
TO-211 MA-MB	Stud-Hex Base Family (Solid Leads)	A	Archived – JEP 95
TO-212 MA	Stud-Hex Base Family (Solid Leads)	A	Archived – JEP 95
TO-213	Flange-Mounted Header, .200 Spacing	A	September 1976
TO-214	Stud-Hex Base Family (Solid Leads)	A	Archived – JEP 95
TO-215	Coaxial Type	A	June 1971
TO-216	Stud-Mounted Stripline	A	June 1971
TO-217	Stud Rectangular Base Family	A	Archived – JEP 95
TO-218	Flange-Mounted Header	E	June 1986
TO-219	Flange-Mounted Header	B	December 1977
TO-220	Plastic Multi Position Flange Mount Mixed Technology 0.10 in Pitch Package	L.01	December 2020
TO-221 AA-AB	Flat-Mounted Peripheral Leads	A	Archived – JEP 95
TO-222 AA-AB	Header Family (.200 Pin Circle)	A	Archived – JEP 95
TO-223 AA-AB	Header Family (.100 Pin Circle)	A	Archived – JEP 95
TO-224 AA	Disc Family - Peripheral Leads	A	Archived – JEP 95
TO-225	Flat Mounted Family (Peripheral Terminals)	C	Archived – JEP 95
TO-226 AE	Header Family, Flat Index	A	December 1981

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
TO-227 AA-AC	Disc Family Peripheral Leads	A	Archived – JEP 95
TO-228 AA-AC	Stud-Mounted Family (Peripheral Terminals)	A	Archived – JEP 95
TO-229	Stripline Header Family	A	Archived – JEP 95
TO-230 AA-AB	Header Family	B	Archived – JEP 95
TO-231 AA-AB	Stud Hex-Base Family (.100 & .200 Pin Circle)	A	Archived – JEP 95
TO-232 AA-AC	Stud Mounted Radial Lead Family	A	Archived – JEP 95
TO-233	Header Family (.280 Pin Circle)	A	Archived – JEP 95
TO-234 AA-AD	Radial Lead Family	A	Archived – JEP 95
TO-235	Flange Mounted Header Family (.400 Pin Spacing)	A	Archived – JEP 95
TO-236	Plastic Small Outline Package (SOT/SOP), 3 Leads	H	January 1999
TO-237	Header Family, Flat Index	B	October 1979
TO-238	Flange-Mounted Header, Rectangular	D	March 1982
TO-239 AA-AB	Flange Mounted Header Family (Cylindrical Body) .490 Pin Circle	B	Archived – JEP 95
TO-240	Terminal Strip Power Module	B	March 1981
TO-241	Header Family(.100 Pin Circle)	A	Archived – JEP 95
TO-242	Header Family Flange Mounted (.100 Pin Circle)	A	Archived – JEP 95
TO-243	Header Family, Peripheral Terminal	C	July 1986
TO-244	Flange-Mounted Rectangular Base	B	September 1984
TO-245	Header Family, .100 Pin Circle <b>DRAWING NOT AVAILABLE</b>		
TO-246	Header Family, .200 Pin Circle <b>DRAWING NOT AVAILABLE</b>		
TO-247	Flange-Mounted Header Family	F	August 2022
TO-248	Power Module	A	Archived – JEP 95
TO-249	Flange Mounted Family (Rectangular Base)	B	Archived – JEP 95
TO-250	4-Lead DIP .300” Spacing	A	July 1985
TO-251	Header Family, Peripheral Terminals	D	June 2002
TO-252	Flange Mounted Family Surface Mount	F	January 2017
TO-253	Plastic Small Outline Package (SOT/SOP), 4 Leads	D	January 1999
TO-254	Flange-Mounted, Peripheral Leads	A	November 1986
TO-255	Disc Family, Peripheral Leads <b>Not Published</b>		December 1987
TO-256	Flat Mounted Transistor	A	March 1988
TO-257	Flange Mounted Header Family (Peripheral Terminals)	C	September 1996
TO-258	Flange-Mounted 5.08 Spacing	A	February 1988
TO-259	Flange-Mounted Header Family	B	April 1991
TO-260	Ceramic Header Axial 3-Lead	A	April 1989
TO-261	Plastic Small Outline Package SOP/SOT	C	May 2002
TO-262	Flange-Mounted Header Family	A	June 1990
TO-263	Plastic Surface Mounted Header Family	F	September 2013
TO-264	Header Family Insertion Mount (Peripheral Terminals)	B	November 1993
TO-265	3 Lead Flange Mounted Ceramic Power Package	A	June 1993

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

<b>OUTLINE NUMBER</b>	<b>TITLE</b>	<b>ISSUE LETTER</b>	<b>DATE</b>
TO-266	Opto Family Insertion Mount (Peripheral Terminals)	A	April 1994
TO-267	Hermetic Flange Mounted Header Family (Peripheral Terminals) Three Lead, 5.0 Spacing	A	September 1994
TO-268	Header Family Surface Mounted (Peripheral Terminals)	A	June 1995
TO-269	Small Outline Surface Mount (R-PDSO-G4)	A	August 1996
TO-270	Two Lead Surface Mount Power Package	C	July 2008
TO-271	Quad Flat Pack Surface Mount Thermally Enhanced	A	May 1998
TO-272	6-Lead Screw Mount Power Package	B	February 2004
TO-273	Plastic Flange Mounted Package, 3 Leads	B	July 2003
TO-274	Plastic Clip Mounted Package, 3 Leads	A	March 2000
TO-275	Plastic Flange Mounted Power Package, 2 Leads	A	November 2000
TO-276	Ceramic No Lead Chip Carrier	A	January 2001
TO-277	Small Outlines Plastic Surface Mount Package	A	January 2006
TO-278	Thin Profile, 3 Lead Plastic Small Outline Surface Mount	B	November 2006
TO-279	Plastic Surface Mounted Header Family	B	August 2008
TO-280	Flange Mounted Header Family	A	August 2010
TO-281	Fully Molded Flange Header Family Full-Pak	A	November 2011

**MAIN INDEX  
FOR  
JEDEC PUBLICATION NO. 95**

<b>OUTLINE NUMBER</b>	<b>TITLE</b>	<b>ISSUE LETTER</b>	<b>DATE</b>
UO-001	14 Beam Chip	B	Archived – JEP 95
UO-002	16 Beam Chip	B	Archived – JEP 95
UO-003	18 Beam Chip	B	Archived – JEP 95
UO-004	20 Beam Chip	B	Archived – JEP 95
UO-005	22 Beam Chip	B	Archived – JEP 95
UO-006	24 Beam Chip	B	Archived – JEP 95
UO-007	26 Beam Chip	B	Archived – JEP 95
UO-008	28 Beam Chip	B	Archived – JEP 95
UO-009	30 Beam Chip	B	Archived – JEP 95
UO-010	32 Beam Chip	B	Archived – JEP 95
UO-011	12 Beam Chip	B	Archived – JEP 95
UO-012	6 Beam Chip	B	Archived – JEP 95
UO-013	8 Beam Chip	B	Archived – JEP 95
UO-014	10 Beam Chip	B	Archived – JEP 95
UO-015	4 Beam Chip	B	Archived – JEP 95
UO-016	34 Beam Chip	A	Archived – JEP 95
UO-017	Tape Automated Bonding Uncased Outline	A	October 1988
UO-018	Tape Automated Bonding (TAB) Package Family	B	July 1993